

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on page 5, line 3 and ending on page 5, line 9 as follows.

In either of the embodiments **200** or **300** described above, note that there are openings in the base plate **202** or **302** that permit the IC component ~~216~~**222** and **316** respectively to protrude through. An optional tape seal **318** may be installed over these openings as is shown in FIG. 4. This seal may be utilized to preclude off-gassing from the epoxy into the sealed environment inside the assembled disc drive should this present a potential problem. In the integrated structure **300**, the additional layer of epoxy provides even further stiffness to the composite structure **300** compared to structure **200**.